



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SOT-23					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	160	110,000	200 °C + N2	0	0.00
HAST	2,360	241,500	130 °C, 85 % RH	0	0.00
Pressure Pot	13,080	1,255,680	121°, 15 PSIG	0	0.00
Solder Dunk	72,651	218,073	260 °C, 10 s	0	0.00
Solderability	1,775	13,630	883 M2003	0	0.00
Temp. Cycle	15,015	5,060,000	- 65 °C to 150 °C	0	0.00